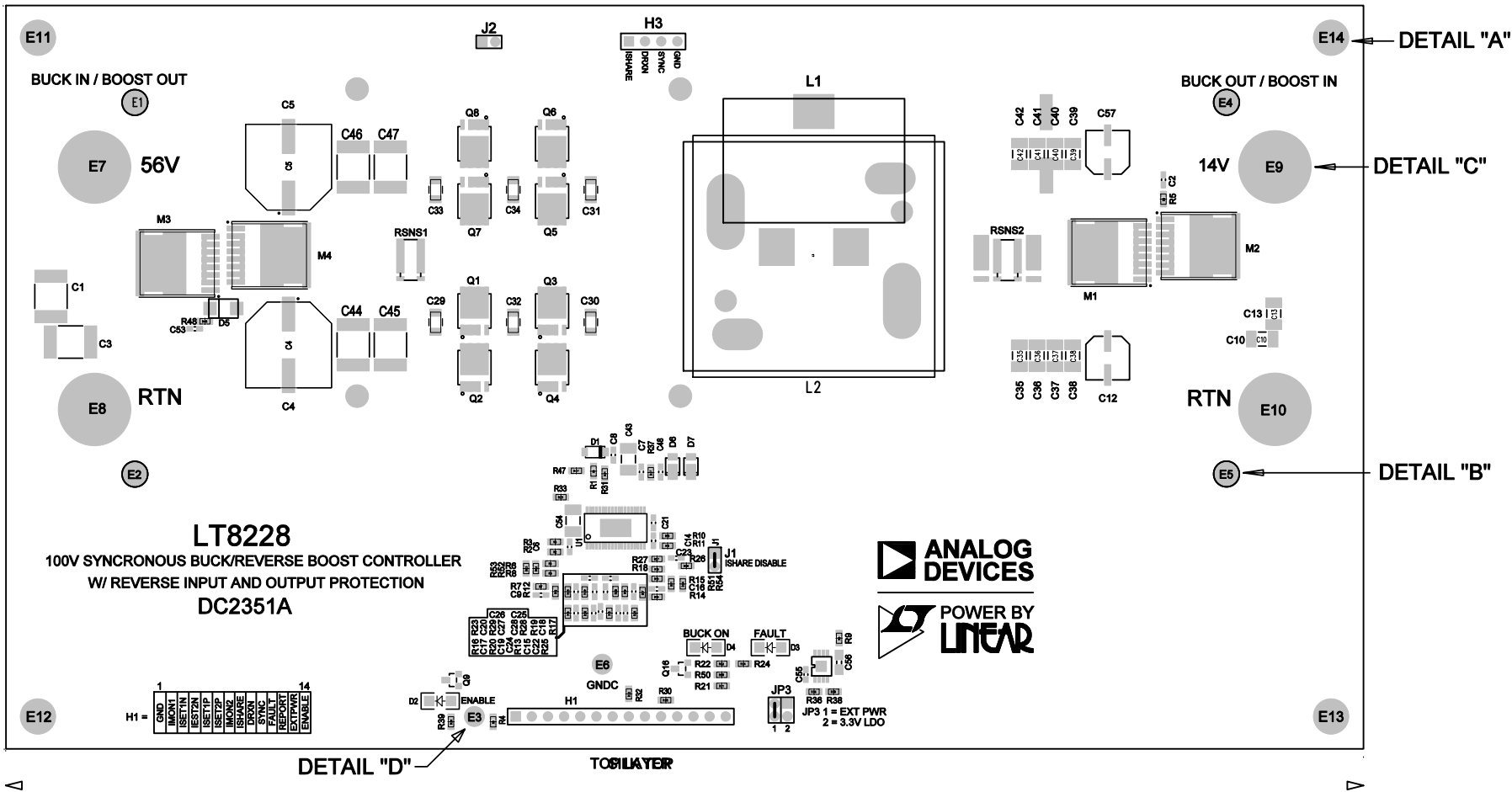
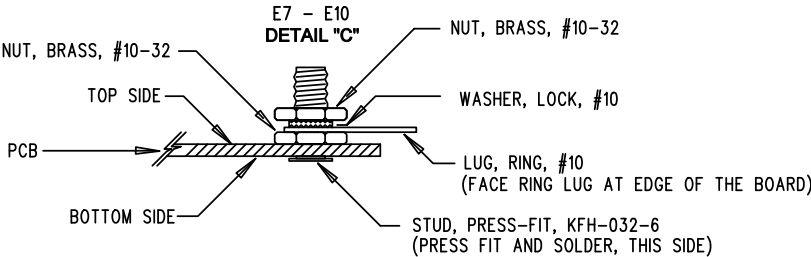
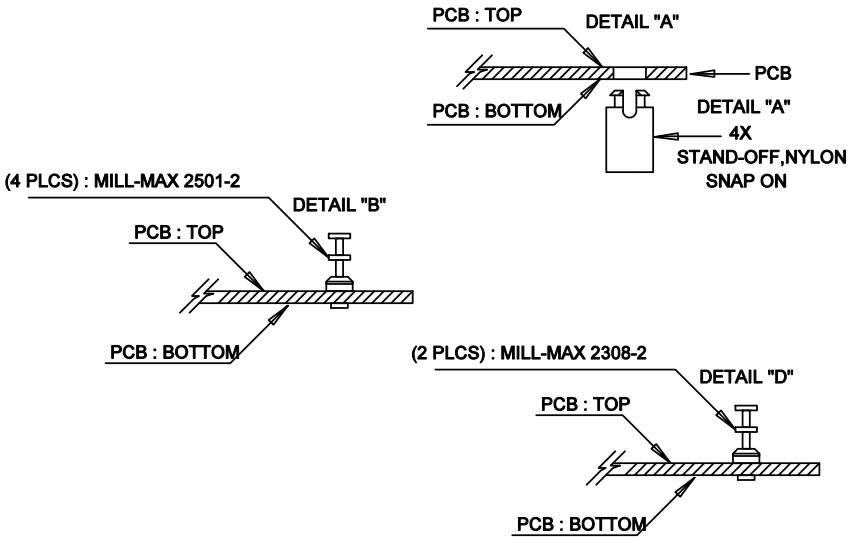




REVISION HISTORY				
ECO	REV	DESCRIPTION	APPR	DATE
-	04	PRODUCTION	CG	09-30-19



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610. MAXIMUM SOLDER TEMPERATURE IS 240 DEG C.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPROVALS		 ANALOG DEVICES		 POWER BY LINEAR		1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 WWW.ANALOG.COM	
PCB DES.	MF	TITLE: 100V SYNCHRONOUS BUCK/REVERSE BOOST CONTROLLER W/ REVERSE INPUT & OUTPUT PROTECTION					
APP ENG.	CG						
		SIZE	IC NO.				REV.
		N/A	LT8228 DEMO CIRCUIT DC2351A				04
SCALE = NONE		FILENAME: DC2351A.PCB				SHT 1 of 2	